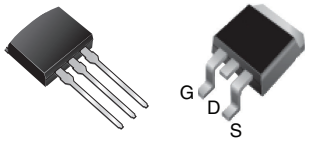
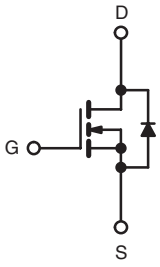
Power MOSFET

PRODUCT SUMMARY		
V_{DS} (V)	900	
$R_{DS(on)}$ (Ω)	V_{GS} = 10 V	8.0
Q_g (Max.) (nC)	38	
Q_{gs} (nC)	4.7	
Q_{gd} (nC)	21	
Configuration	Single	

I²PAK (TO-262) **D²PAK (TO-263)**





N-Channel MOSFET

FEATURES

- Surface Mount (IRFBF20S/SiHFBF20S)
- Low-Profile Through-Hole (IRFBF20L/SiHFBF20L)
- Available in Tape and Reel (IRFBF20S/SiHFBF20S)
- Dynamic dV/dt Rating
- 150 °C Operating Temperature
- Fast Switching
- Fully Avalanche Rated
- Lead (Pb)-free Available

Available

RoHS* COMPLIANT

DESCRIPTION

Third generation Power MOSFETs form Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The D²PAK is a surface mount power package capabel of the accommodating die sizes up to HEX-4. It provides the highest power capability and the lowest possible on-resistance in any existing surface mount package. The D²PAK is suitable for high current applications because of its low internal connection resistance and can dissipate up to 2.0 W in a typical surface mount application. The through-hole version (IRFBF20L/SiHFBF20L) is available for low-profile applications.

ORDERING INFORMATION				
Package	D²PAK (TO-263)	D²PAK (TO-263)	D²PAK (TO-263)	I²PAK (TO-262)
Lead (Pb)-free	IRFBF20SPbF	IRFBF20STRLPbF[a]	IRFBF20STRRPbF[a]	IRFBF20LPbF
	SiHFBF20S-E3	SiHFBF20STL-E3[a]	SiHFBF20STR-E3[a]	SiHFBF20L-E3
SnPb	IRFBF20S	IRFBF20STRL[a]	IRFBF20STRR[a]	IRFBF20L
	SiHFBF20S-E3	SiHFBF20STL[a]	SiHFBF20STR[a]	SiHFBF20L

Note

a. See device orientation.

ABSOLUTE MAXIMUM RATINGS T_C = 25 °C, unless otherwise noted					
PARAMETER			**SYMBOL**	**LIMIT**	**UNIT**
Drain-Source Voltage[e]			V_{DS}	900	V
Gate-Source Voltage[e]			V_{GS}	± 20	
Continuous Drain Current	V_{GS} at 10 V	T_C = 25 °C	I_D	1.7	A
		T_C = 100 °C		1.1	
Pulsed Drain Current[a,e]			I_{DM}	6.8	
Linear Derating Factor				0.43	W/°C
Single Pulse Avalanche Energy[b, e]			E_{AS}	180	mJ
Repetitive Avalanche Current[a]			I_{AR}	1.7	A
Repetitive Avalanche Energy[a]			E_{AR}	5.4	mJ
Maximum Power Dissipation	T_C = 25 °C		P_D	54	W
	T_A = 25 °C			3.1	
Peak Diode Recovery dV/dt[c, e]			dV/dt	1.5	V/ns

* Pb containing terminations are not RoHS compliant, exemptions may apply

ABSOLUTE MAXIMUM RATINGS T_C = 25 °C, unless otherwise noted				
PARAMETER		**SYMBOL**	**LIMIT**	**UNIT**
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to + 150	°C
Soldering Recommendations (Peak Temperature)	for 10 s		300[d]	
Mounting Torque	6-32 or M3 screw		10	N

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
b. V_{DD} = 50 V; starting T_J = 25 °C, L = 117 mH, R_G = 25 Ω, I_{AS} = 1.7 A (see fig. 12).
c. $I_{SD} \leq$ 1.7 A, dI/dt ≤ 70 A/µs, $V_{DD} \leq V_{DS}$, $T_J \leq$ 150 °C.
d. 1.6 mm from case.
e. Uses IRFBF20/SiHFBF20 data and test conditions.

THERMAL RESISTANCE RATINGS				
PARAMETER	**SYMBOL**	**TYP.**	**MAX.**	**UNIT**
Maximum Junction-to-Ambient (PCB Mounted, steady-state)[a]	R_{thJA}	-	40	°C/W
Maximum Junction-to-Case	R_{thJC}	-	2.3	

Note

a. When mounted on 1" square PCB (FR-4 or G-10 material).

SPECIFICATIONS T_J = 25 °C, unless otherwise noted							
PARAMETER	**SYMBOL**	**TEST CONDITIONS**		**MIN.**	**TYP.**	**MAX.**	**UNIT**
Static							
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0 V, I_D = 250 µA		900	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to 25 °C, I_D = 1 mA		-	1.1	-	mV/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 µA		2.0	-	4.0	V
Gate-Source Leakage	I_{GSS}	V_{GS} = ± 20 V		-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 900 V, V_{GS} = 0 V		-	-	100	µA
		V_{DS} = 720 V, V_{GS} = 0 V, T_J = 125 °C		-	-	500	
Drain-Source On-State Resistance	$R_{DS(on)}$	V_{GS} = 10 V	I_D = 1.0 A[b]	-	-	8.0	Ω
Forward Transconductance	g_{fs}	V_{DS} = 50 V, I_D = 1.0 A[b]		0.6	-	-	S
Dynamic							
Input Capacitance	C_{iss}	V_{GS} = 0 V, V_{DS} = 25 V, f = 1.0 MHz, see fig. 5		-	490	-	pF
Output Capacitance	C_{oss}			-	55	-	
Reverse Transfer Capacitance	C_{rss}			-	18	-	
Total Gate Charge	Q_g	V_{GS} = 10 V	I_D = 1.7 A, V_{DS} = 360 V, see fig. 6 and 13[b]	-	-	38	nC
Gate-Source Charge	Q_{gs}			-	-	4.7	
Gate-Drain Charge	Q_{gd}			-	-	21	
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 450 V, I_D = 1.7 A, R_G = 18 Ω, V_{GS} = 10 V, see fig. 10[b]		-	8.0	-	ns
Rise Time	t_r			-	21	-	
Turn-Off Delay Time	$t_{d(off)}$			-	56	-	
Fall Time	t_f			-	32	-	

SPECIFICATIONS T_J = 25 °C, unless otherwise noted						
PARAMETER	**SYMBOL**	**TEST CONDITIONS**	**MIN.**	**TYP.**	**MAX.**	**UNIT**
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 	-	-	1.7	A
Pulsed Diode Forward Current[a]	I_{SM}		-	-	6.8	
Body Diode Voltage	V_{SD}	T_J = 25 °C, I_S = 1.7 A, V_{GS} = 0 V[b]	-	-	1.5	V
Body Diode Reverse Recovery Time	t_{rr}	T_J = 25 °C, I_F = 1.7 A, dI/dt = 100 A/µs[b]	-	350	530	ns
Body Diode Reverse Recovery Charge	Q_{rr}		-	0.85	1.3	µC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)				

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).

b. Pulse width ≤ 300 µs; duty cycle ≤ 2 %.

c. Uses IRFBF20/SiHFBF20 data and test conditions.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

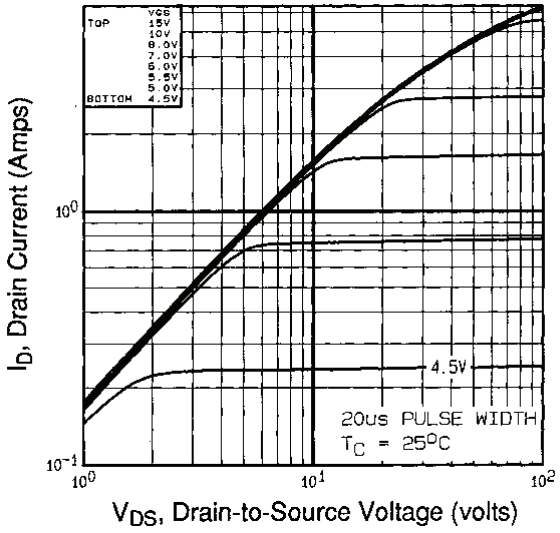


Fig. 1 - Typical Output Characteristics

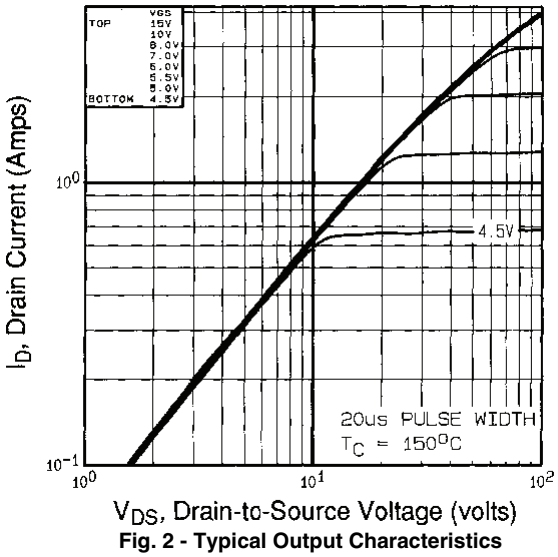


Fig. 2 - Typical Output Characteristics

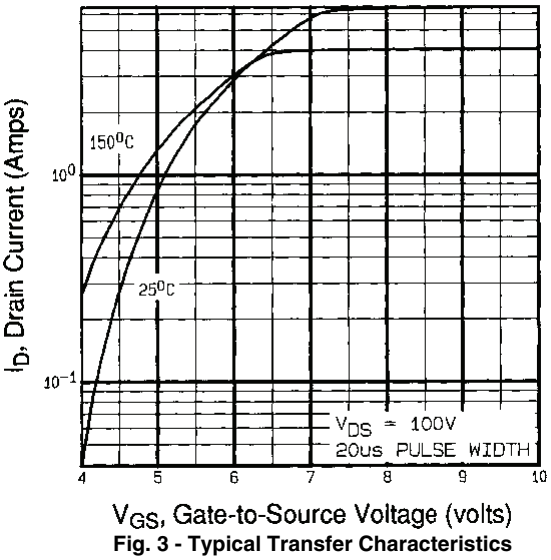


Fig. 3 - Typical Transfer Characteristics

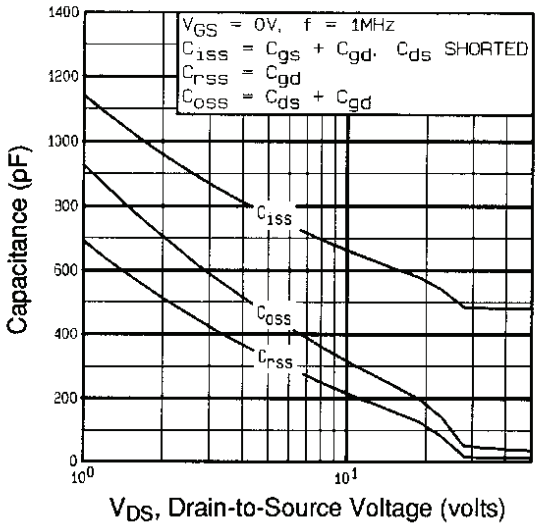


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

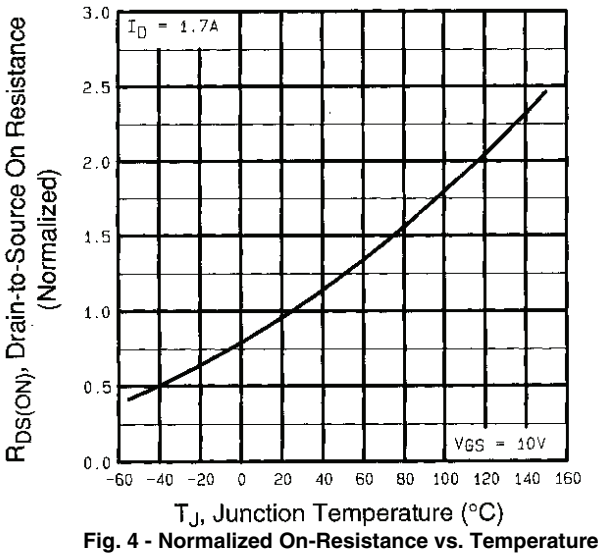


Fig. 4 - Normalized On-Resistance vs. Temperature

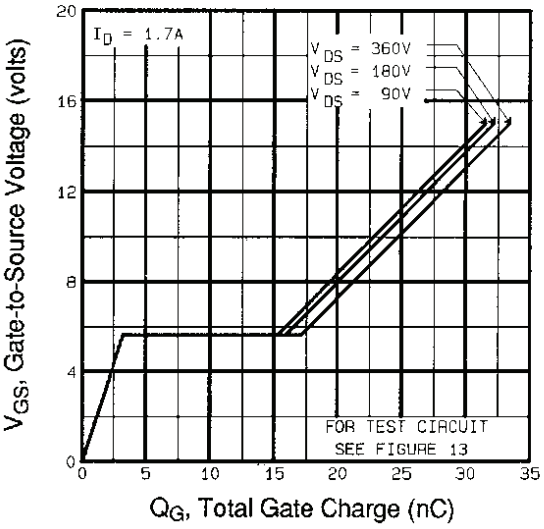


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

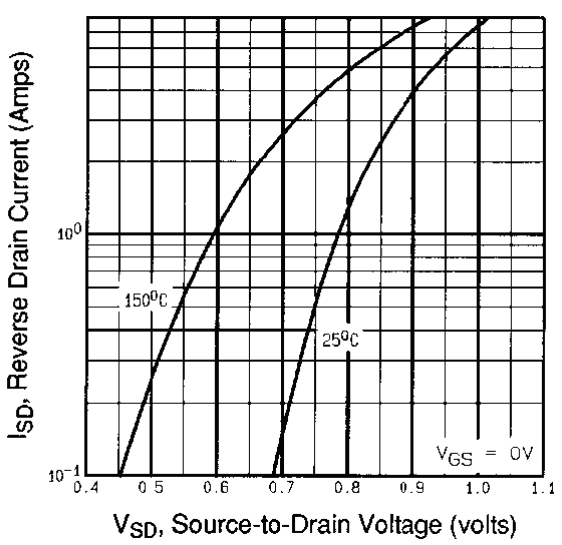


Fig. 7 - Typical Source-Drain Diode Forward Voltage

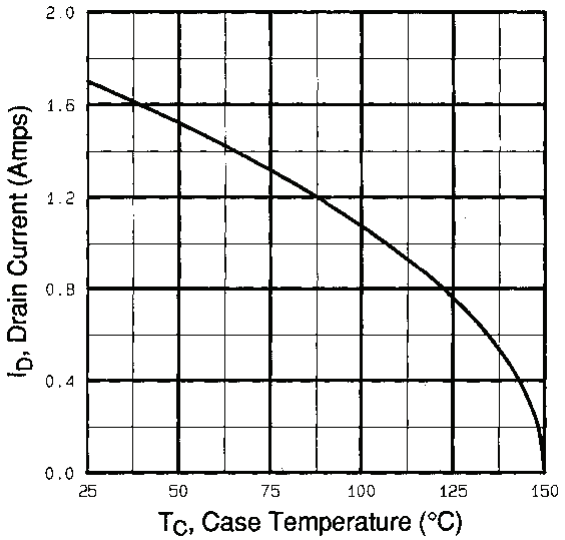


Fig. 9 - Maximum Drain Current vs. Case Temperature

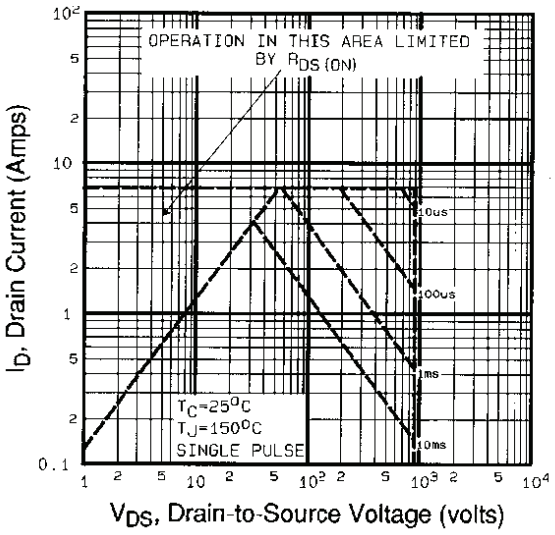


Fig. 8 - Maximum Safe Operating Area

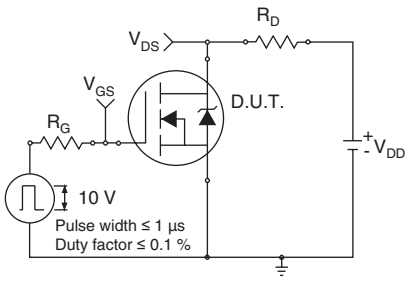


Fig. 10a - Switching Time Test Circuit

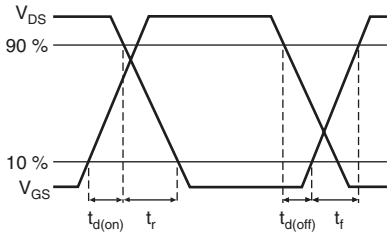


Fig. 10b - Switching Time Waveforms

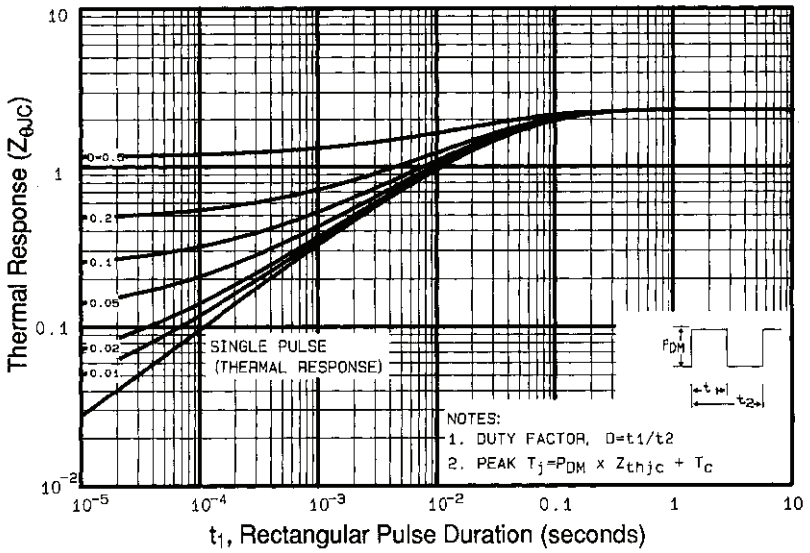


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

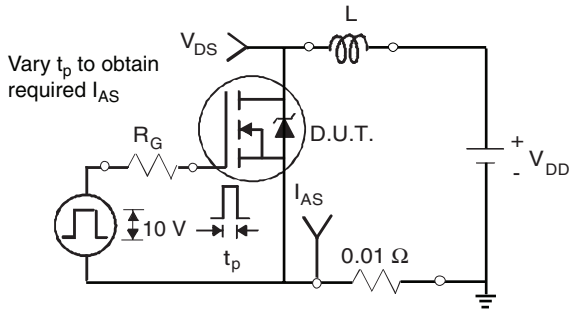


Fig. 12a - Unclamped Inductive Test Circuit

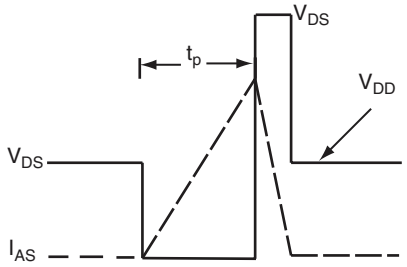


Fig. 12b - Unclamped Inductive Waveforms

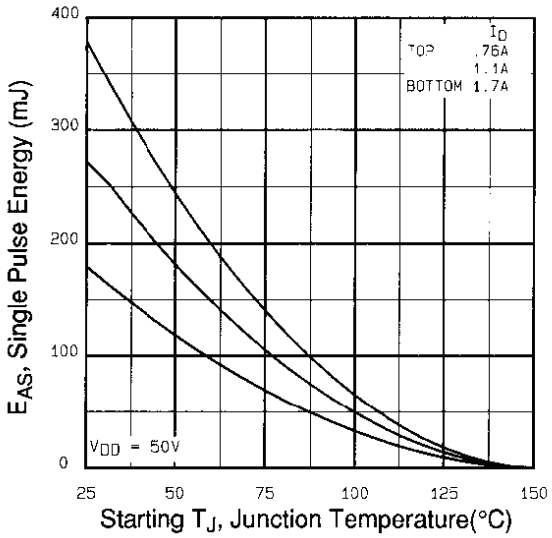


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

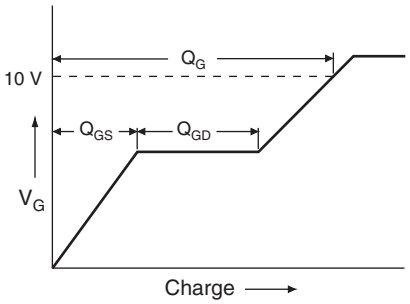


Fig. 13a - Basic Gate Charge Waveform

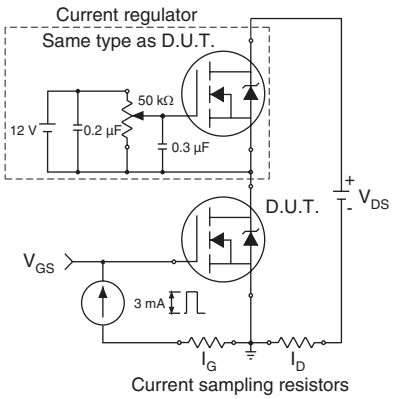
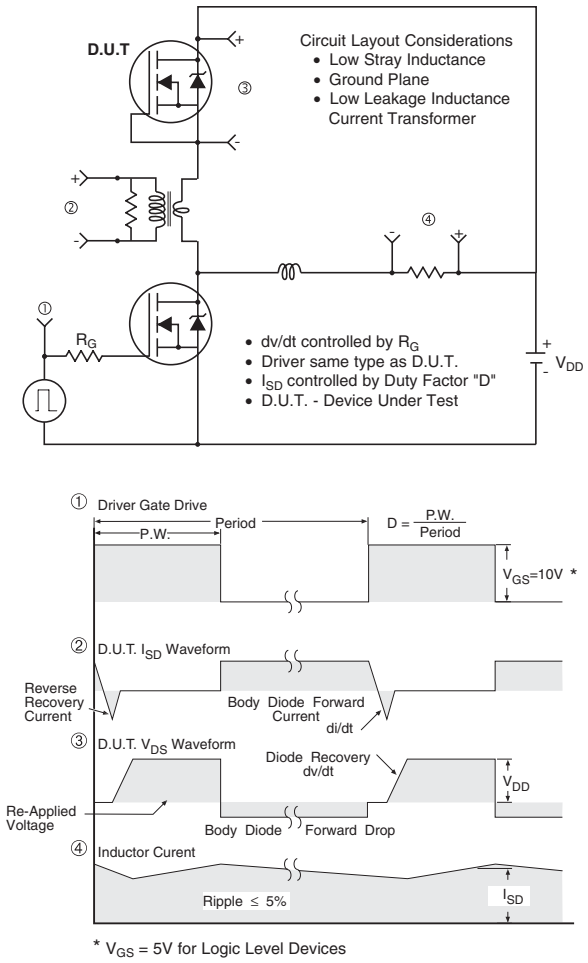


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dv/dt Test Circuit



* V_{GS} = 5V for Logic Level Devices

Fig. 14 - For N-Channel

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